



(Korea)

EV Group brings EVG®40 NT2 automated metrology system to 3D heterogeneous integration - November 17, 2021

EVG unveiled the EVG®40 NT2 automated metrology system, which provides overlay and CD measurements for W2W, D2W and D2D bonding as well as maskless lithography applications. Designed for high-volume production with feedback loops for real-time process correction and optimization, the EVG40 NT2 helps device manufacturers, foundries and packaging houses accelerate the introduction of new 3D/heterogeneous integration products as well as improve yields and avoid scrapping of highly valuable wafers. The EVG40 NT2 system provides highly precise measurements of critical bonding and lithography process parameters for current and future leading-edge 3D/heterogeneous integration applications. For alignment verification, the EVG40 NT2 generates an overlay model that can be used in a feedback loop for improving overall alignment.



#디지털트윈 #산업용사물인터넷 #TSN #모니터링 #로보틱스 #자율주행 #모빌리티 #ENGLISH NEWS

EV 그룹, 3D 이종집적화 지원 EVG40 NT2 자동 계측 시스템 발표
 EVG40 NT2, 웨이퍼 및 다이 수준의 하이브리드 본딩과 마스크리스 리소그래피 구현을 가속화하는 계측 기술
 by 오승모 기자 | 2021-11-17



EVG®40 NT2 자동 계측 시스템

MEMS, 나노 기술, 반도체 제조를 웨이퍼 본딩 및 리소그래피 장비의 선도적 공급사인 EV 그룹(이하 EVG)이 EVG®40 NT2 자동 계측 시스템을 발표했다.

a
지
llc
한

Typ

ICP

추진

